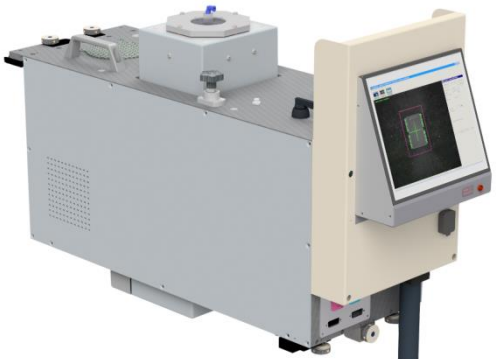
3D-VISION

Optical measurement of components



Depending on the customer requirement, the individual components can be measured by the 3D-VISION module for optical checks in 2D and 3D (geometric dimensions, leads, pads, etc.). If during this process components are identified as defective, they can be sorted out via the axis system directly into another module or stored temporarily for future retesting.

Product description/functions

- Optical measurements of leaded/leadless packages: SOIC, QFP, TQFP, QFN, BGA
- Complete 2D and 3D measurement of the geometric properties of the components, amongst others, geometric dimensions, lead components, stand-off, coplanarity, pitch
- Camera system with three integrated cameras, LED object lighting
- Alignment of the three cameras on the individual component: 1x directly, 2x at an angle
- “On-the-fly” passage of the module by the axis system without stop at full speed
- At this time, “on-the-fly” scanning of the optical properties of the component: Automatic triggering of the exposure, incl. object lighting depending on the axis positions, data acquisition
- Immediate sending of the camera exposures and acquired data to the control PC as well as automatic analysis of the acquired data
- Feedback after analysis of the acquired data whether a component is defective
- Separate image processing program of the module: alternative control via monitor on the module
- Monitor and ports (USB, control signals, LAN etc.) – at the front

Options

Component exposure	Component exposure for offline operation

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BOS Technology GmbH • Ansbacher Str. 5 · 10787 Berlin, Germany • Manufacturing site: Alexander-Meissner-Str. 36 · 12526 Berlin, Germany
+49 (0)30 53 88 09 0 • info@bos-berlin.de • www.bos-berlin.de

Technical data

Dimensions W/H/D [approx. mm]	280 x 560 x 910
Weight	40 kg
Media:	
AC	230 V
DC	24 / 12 V
Compressed air	6 bar
Vacuum	internal
Other	Ethernet 100 Mb

Accessories

- Cover / Spacing standard
- Calibration system
- Calibration standard

Detailed drawings